



PATENT
8013-1147

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Hirokazu HONDA

Conf. 7187

Application No. 09/678,609

Group 2822

Filed October 4, 2000

Examiner David E. Graybill

MULTILAYER INTERCONNECTION BOARD, SEMICONDUCTOR
DEVICE HAVING THE SAME, AND METHOD OF FORMING THE
SAME AS WELL AS METHOD OF MOUNTING THE SEMICONDUCTOR
CHIP ON THE INTERCONNECTION BOARD

RESPONSE

Assistant Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

February 17, 2005

Sir:

In response to the Office Action mailed November 12,
2004, the applicant and assignee provide the requested
information.

The Claims are listed in the listing that begins on
page 2 of this paper.

Remarks begin on page 12 of this paper.